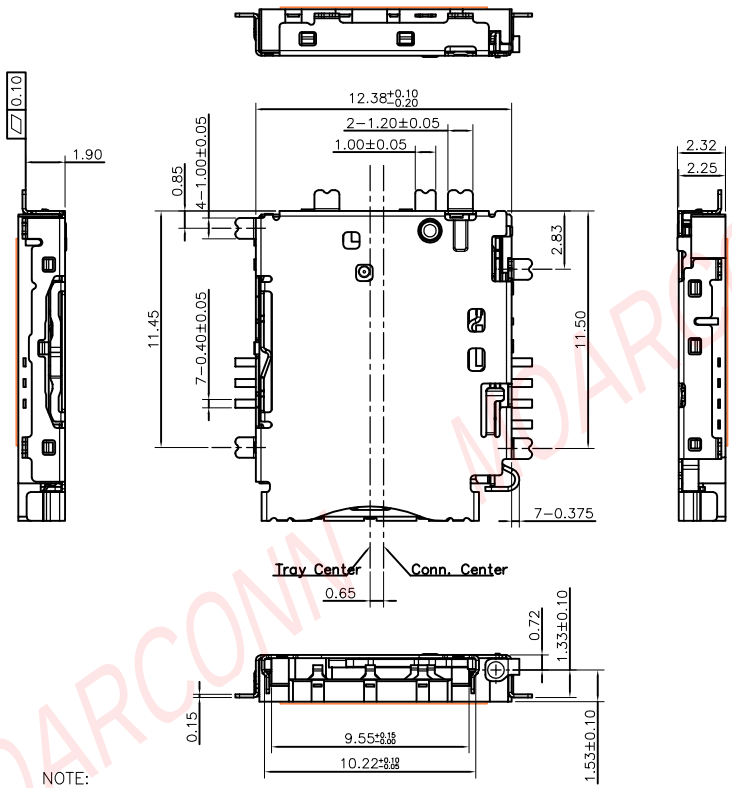
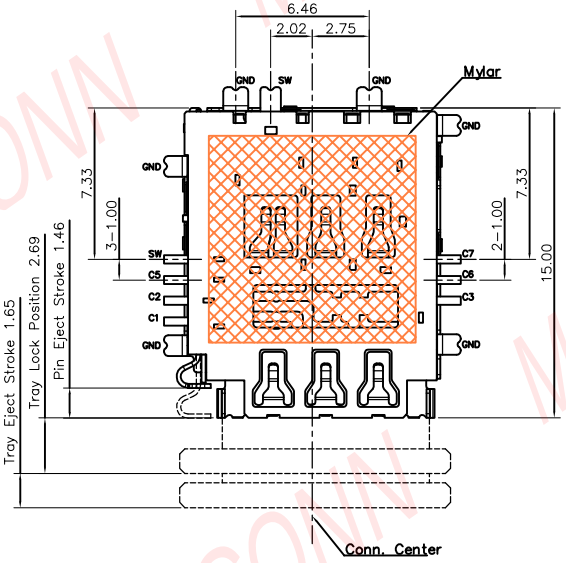
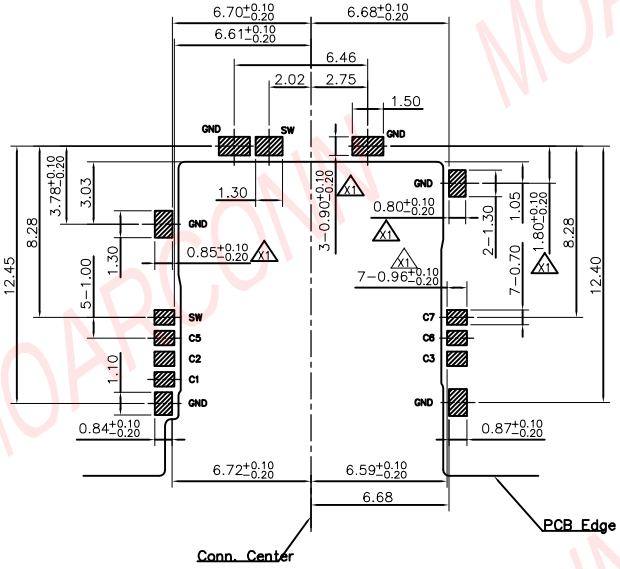
All materials, plating and process meet HF requirements.







Recommended PCB Layout
Mount Surface Top View
General Tolerance ±0.05 Pad Area

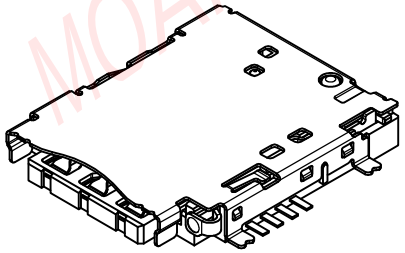
NOTE:

1. Material:
   1−1 Housing:High Temperature Thermoplastic,(LCP S475)Color Black UL 94V−0
   1−2 Contact: Phosphor Bronze(C5210R−H,T=0.08±0.01mm)
   1−3 Cover: SUS301−H T=0.15±0.03mm
2. Plating:
   2−1 Contact terminal:
   Contact area: Gold 1u" Min.
   Solder area: Gold Flash
   Underplating: Ni overall 50u" Min.
   2−2 Cover:
   Underplating: Weldable Ni overall 50u" Min.
3. Specification:
   3−1.Current Rating :0.5A max.
   3−2.Contact Resistance: 50 mOhms max
   3−3.Insulation Resistance:1000 MOhms min./500VDC
   3−4.Dielectric Withstanding Voltage:500 V AC/1minute
   3−5.Operating Temperature:−25°C to+85°C
   3−6.Mating Cycles:5000 Insertions
4. Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC
5. Recommending A Metal More Than 0.15mm Thick.
   Please Confirm Solderadility, If Use A Metal Mask Less Than 0.15mm Thick.

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA

COMPOSITION OF DETECTION
CARD DETECT(SW)
C5 ○—/—○ SW
CARD DETECTION/SWITCH
CARD INSTALLATION:ON
NON CARD:OFF



REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X0	-------	NEW RELEASE	Alexander	2025.06.12

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2°

MOARCONN®
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DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

PRODUCT NAME : NanoSIM Bottom Sink 1.9 SMT	DRAWING: Alexander	DATE: 2025.08.25
PRODUCT NO. : NS225−T1150−01	CHECK:	DATE:
DRAWING NO. : D−NS225−T1150−01	APPROVED:	DATE:

SCALE:	DWG ID:	REV.:	PAGE:
1:1	C D	X0	1 OF 1

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